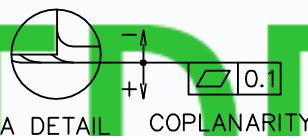
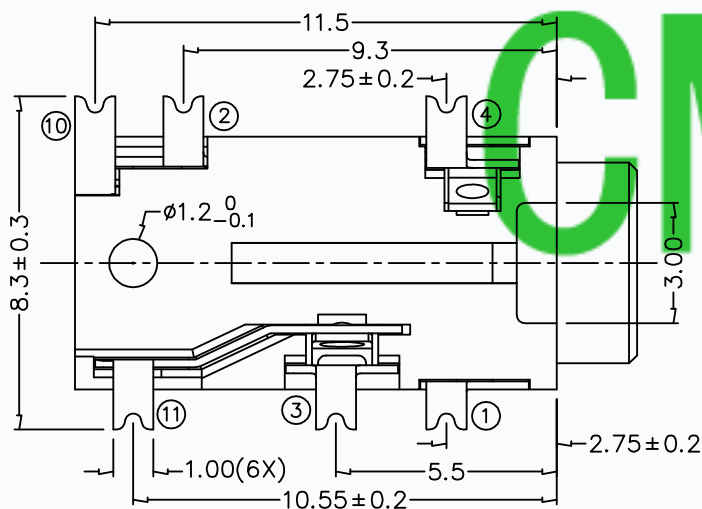
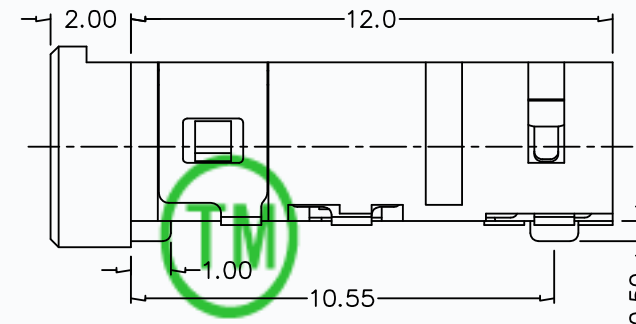
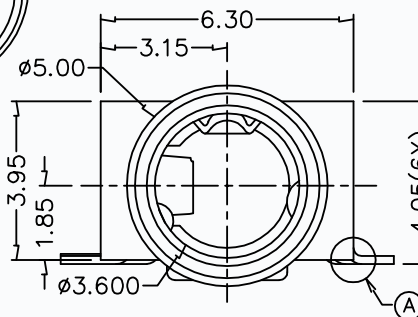
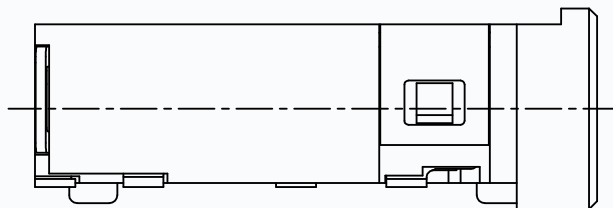
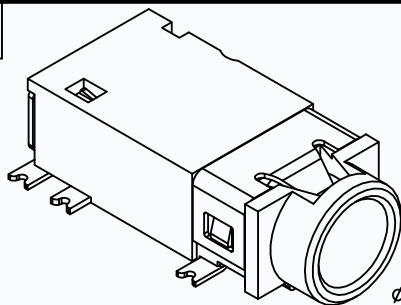


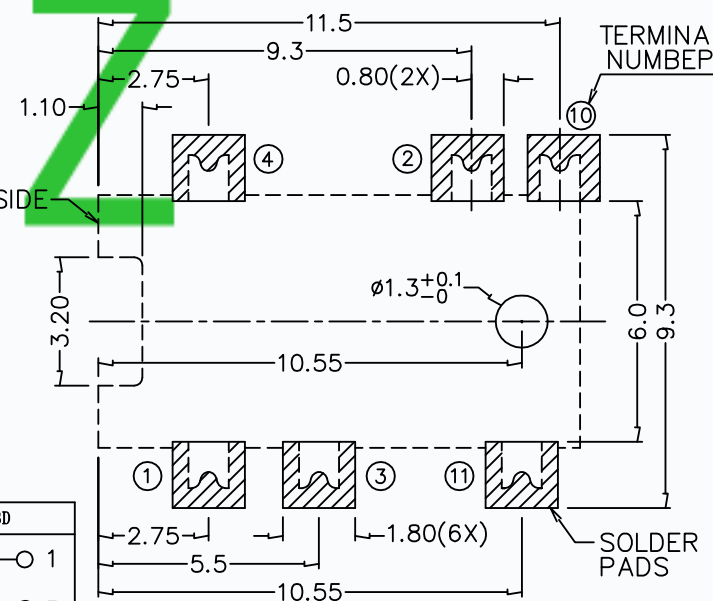
CAD FILE:



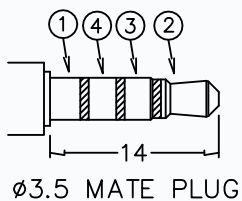
P.C.B LAYOUT SIDE

\* MATERIAL

- TERMINAL 1 : COPPER ALLOY
- TERMINAL 2 : COPPER ALLOY
- TERMINAL 3 : COPPER ALLOY
- TERMINAL 4 : COPPER ALLOY
- TERMINAL 10 : COPPER ALLOY
- TERMINAL 11 : COPPER ALLOY
- HOUSING : PA6T



RECOMMENDED SOLDER PAD LAYOUT



MODEL NO.	T13-35956D	T13-35955AD	T13-35955BD	T13-35954D	T13-35953D
SCHEMATIC					

APPD.	DESCRIPTIONS OF REVISION

**TOLERANCE  
UNLESS SPECIFIED**  
 WITHIN 1.5mm : ±0.1mm  
 OVER 1.5mm : ±0.2mm

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**TITLE : 3.5mm SMD PHONE JACK**  
**MODEL: T13-3595D**  
**CMTDDZ 东莞市田都电子有限公司**  
 DONGGUAN TIANDU ELECTRONICS CO.,LTD.

UNIT : mm	DRWG NO.: CMTDDZ-T13-3595D-00
SCALE: 3:1	DWN. ERIC 2013-6-17
APPD. Coco	CHK'D MAIKO 2013-6-17
	2013-6-17